

Receipt

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

Tsuga et al.

Filed: 02/28/02

Serial No.: 10/085,753

Title: METHOD AND DEVICE FOR REMOVING PARTICLES ON
SEMICONDUCTOR WAFERS



Docket No.: TI-31620

Examiner:

Art Unit:

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TBD JUL 10 2002
TC 2800 MAIL ROOM

REQUEST FOR CORRECTED FILING RECEIPT

Assistant Commissioner for Patents
Washington, DC 20231

Attn: Office of the Initial Patent Examination's
Customer Service Center

Sir:

MAILING CERTIFICATE UNDER

37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service as First Class
Mail in an envelope addressed to: Assistant
Commissioner of Patents, Washington, D.C. 20231 on:

Marianna Smith 6-6-02

Marianna Smith

Date

Enclosed is a photocopy of the filing receipt received from the United States Patent and Trademark office in the above-identified application. The filing receipt is erroneous in that the first named inventor's name is spelled incorrectly. A copy of the declaration is enclosed showing the correct spelling.

Phrase should read: Applicant(s)

Toshihito Tsuga, Tsuchiura-shi, JAPAN;

Minoru Fube, Hayami-gun, JAPAN;

Kazutaka Nakayama, Hayami-gun, JAPAN;

Applicants respectfully solicit a corrected filing receipt from the United States Patent and Trademark Office, and request that no fees are necessary for the above change.

Respectfully submitted,

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/085,753 /	02/28/2002 /	2812	740	TI-31620	2	9	2

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CONFIRMATION NO. 8409

FILING RECEIPT



OC000000007732489

Date Mailed: 03/28/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 03/27/2002

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

Title

Method and device for removing particles on semiconductor wafers ✓

Preliminary Class

438

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